

PREPARED BY: <i>y. Hasegawa</i>	DATE: <i>May 16, 1994</i>	<h1>SHARP</h1> <p>ELECTRONIC COMPONENTS GROUP SHARP CORPORATION</p> <h2>SPECIFICATION</h2>	SPEC. No. ED-94030 <i>5/20</i>
APPROVED BY: <i>J. Yoshikawa</i>	DATE: <i>May 16, 1994</i>		ISSUE May 16, 1994
			PAGE 14 Pages
			REPRESENTATIVE DIVISION OPTO-ELECTRONIC DEVICES DIV.

DEVICE SPECIFICATION FOR
PHOTOCOUPRER

MODEL No.
PC928

(Business dealing mme : PC928)

REFERENCE

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2. Please obey the instructions mentioned below for actual use of this device.

Con tact a SHARP representative of sales office in advance when you intend to use SHARP devices for any applications other than those applications for general electronic equipment recommend by SHARP at (I).

 - (1) This device is designed for general electronic equipment.

Main uses of this device are as follows:

 - .OA equipment .AV equipment .Home appliance . Telecommunication
 - [eq. "pine]: (Terminal) .Measuring equipment .Tooling machine .Computer, etc.]
 - (2) Please take proper steps in order to maintain reliability and safety, in case this device is used for the uses mentioned below which require high reliability.
 - .Unit concerning control and safety of a vehicle (air plane, train, automobile etc.)
 - .Gas leak detection breaker .Traffic signal .Fire box and burglar alarm box
 - [.Other safety equipment, etc.]
 - (3) Please do not use for the uses mentioned below which require extremely high reliability.
 - . Space equipment . Telecommunication equipment (Trunk)
 - [.Nuclear control equipment .Medical equipment etc.]

CUSTOMER'S APPROVAL

DATE

PRESENTED
BY

T. Matsumura

DATE

BY

T. Matsumura,
Department General Manager of
Engineering Dept.,II
Opto-Electronic Devices Div.
ELECOM Group
SHARP CORPORATION

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RECORDS OF REVISION

MODEL No. PC928

6/20

FIRST ISSUE May 16, 1994

IDENT. DATA No. ED-94030

DATE	REF. PAGE PARAGRAPH DRAWING NO	REVISEI No.	SUMMARY	CHECK & APPROVAL
May. 16 1994			Establish	J.M
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7/20

MODEL No.

PC928

PAGE

1

1. Application

This specification applies to the outline and characteristics of photocoupler Model No. PC928.

REFERENCE

2. Outline

Refer to the attached drawing No. CY6805K02.

3. Ratings and characteristics

Refer to the attached sheet, page 5 to 11.

4. Reliability

Refer to the attached sheet, page 12.

5. Incoming inspection

Refer to the attached sheet, page 13.

6. Supplement

6.1 Isolation voltage shall be measured in the following method,

- (1) Short between pins 1 and 7 on the primary side and between pins 8 to 14 on the secondary side.
- (2) The dielectric withstand tester with zero-cross circuit shall be used.
- (3) The wave form of applied voltage shall be a sine wave.
(It is recommended that the isolation voltage be measured in insulation oil.)

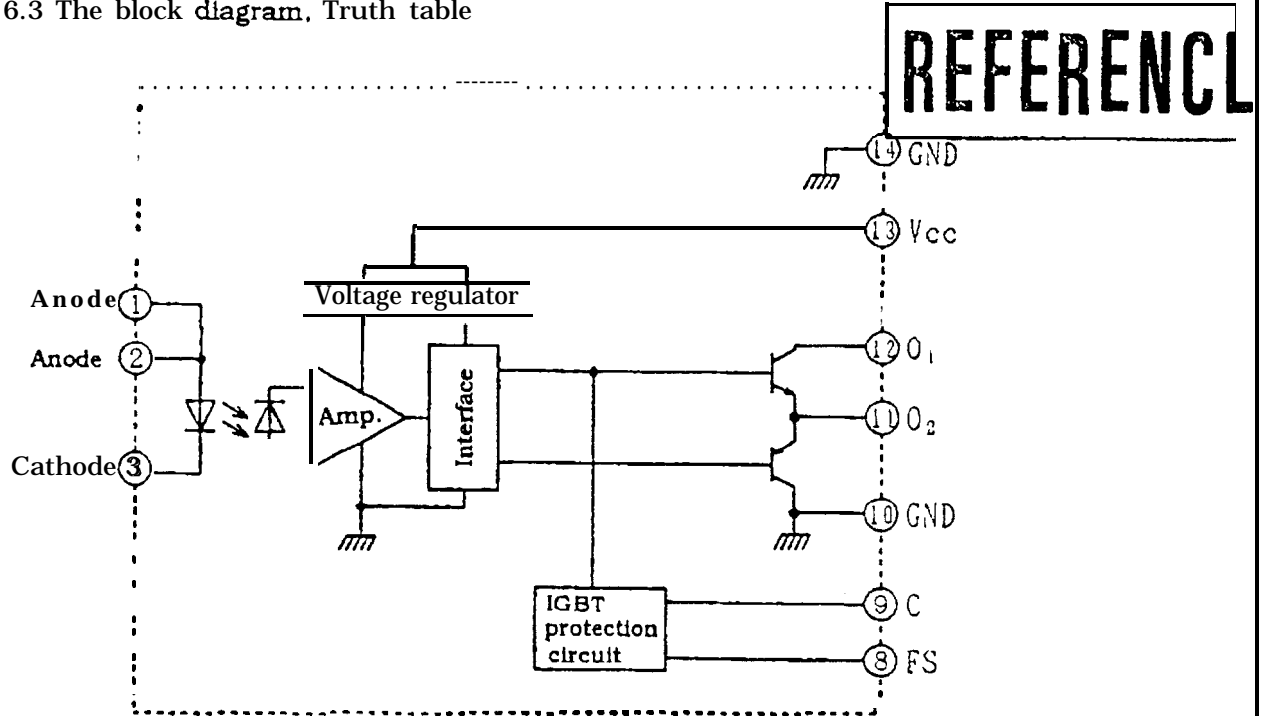
6.2 The business dealing name used for this product when ordered or delivered shall be PC928.

8/20

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MODEL No. PC928	PAGE 2
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6.3 The block diagram, Truth table



Troth table

Input	c input-output	O ₂ output	FS output	
ON	Low level	High level	High level	
	High level	Low level	Low level	At operating protection function
OFF	Low level	Low level	High level	
	High level	Low level	High level	

6.4 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product Incorporates non-coherent light emitting diode.

9/20

SHARP CORPORATION

MODEL No.

PC928

PAGE

3

7. Notes

7.1 For cleaning

(1) Solvent cleaning : Solvent temperature 45°C or less
Immersion 3 min. or less

(2) Ultrasonic cleaning : The affect to device by ultrasonic cleaning is different by cleaning bath size, ultrasonic power output, cleaning time, PWB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.

Applicable solvent : Ethyl alcohol, Methyl alcohol
Freon TE·TF, Diflon-solvent S3-E

Please refrain from using Chloro Fluoro Carbon type solvent to clean device as much as possible since it is internationally restricted to protect the ozoneosphere. Before you use alternative solvent you are requested to confirm that it does not attack package resin.

7.2 Please use the same as normal integration circuit about static electricity in order that this device is OPIC photocoupler.

7.3 In order to stabilize power supply line, we recommend to connect a by-pass capacitor of 0.01 μ F or more between Vcc and GND near the device.

7.4 Precaution for Soldering Photocoupler

Refer to the attached sheet, page 14.

8. Others

Any doubt as to this specification shall be determined in good faith upon mutual consultation of the both parties.

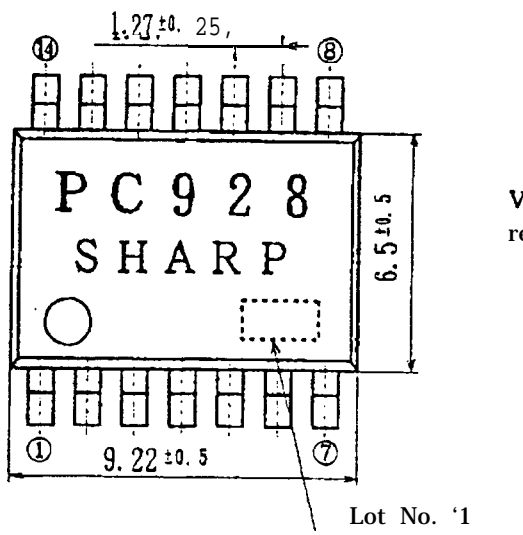
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10/20

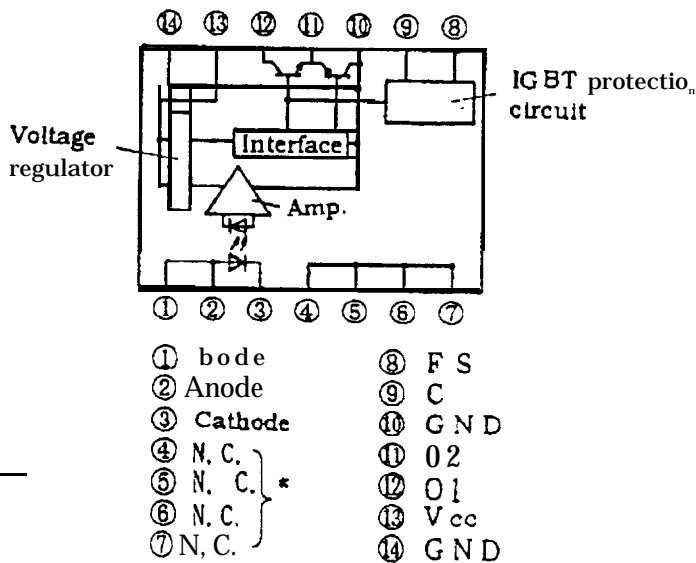
SHARP CORPORATION

MODEL No. PC928	PAGE 4
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REFERENCE

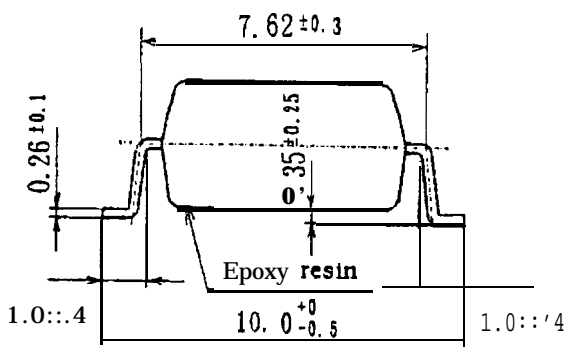
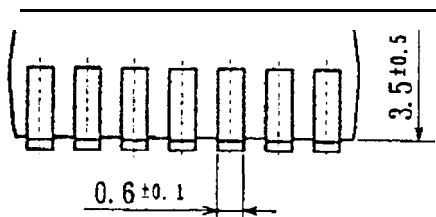


Pin Nos. and internal connection diagram



- ① bode
- ② Anode
- ③ Cathode
- ④ N. C.
- ⑤ N. C. *
- ⑥ N. C.
- ⑦ N. C.
- ⑧ F S
- ⑨ C
- ⑩ GND
- ⑪ 02
- ⑫ 01
- ⑬ Vcc
- ⑭ GND

● 4 to 7 pin : Common



• 1) 2-digit number marked according to DIN standard.

UNIT: 1/1 mm	
Name	PC928 Outline Dimensions
Drawing No.	CY6805K02

SHARP CORPORATION

MODEL NO,

PC928

PAGE

5

3. Ratings and characteristics

3.1 Absolute maximum ratings

W

	Parameter	Symbol	Rating	Unit
Input	*1 Forward current	I_F	25	mA
	Reverse voltage	V_R	6 (Ta=25°C)	v
output	Supply voltage	Vcc	35	v
	O ₁ Output current	I _{O1}	0.1	A
	*4 O ₁ Peak output current	I _{OP}	0.4	A
	O ₂ Output current	I _{O2}	0.1	A
	*4 O ₂ Peak output current	I _{OP}	0.4	A
	O ₁ Output voltage	V _{O1}	35	v
	*2 Power dissipation	P _O	600	mW
	Overcurrent detection voltage	V _c	Vcc	v
	Overcurrent detection current	I _c	30	mA
	Error signal output voltage	V _{FS}	Vcc	v
	Error signal output current	I _{FS}	20	mA
	*3 Total power dissipation	P _{tot}	550	mW
● 5 Isolation voltage	V _{iso}	4.0	kV _{rms}	
Operating temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-55 to 125	°C	
Soldering temperature	T _{sol}	260 (for 10s)	°C	

● 1, 2, 3 The derating factors of absolute maximum ratings due to ambient temperature are shown in Fig. 1, 2, 3.

*4 Pulse width $\leq 0.15 \mu s$, Duty ratio : 0.01

*5 AC for min., 40 to 60%RH, Ta.25°C

SHARP CORPORATION

MODEL No.

PC928

PAGE

6

REFERENCE

(Unspecified : Ta=Topr)

3.2.1 Electro-optical characteristics(I)

	Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Fig.	Conditions
Input	Forward voltage	V_{F1}	-	1.2	1.4	V	.	$I_F=20mA, Ta=25^\circ C$
		V_{F2}	0.6	0.9	-	v	-	$I_F=0.2mA, Ta=25^\circ C$
	Reverse current	I_R	-	-	10	μA	.	$Ta=25^\circ C, V_R=4V$
	Terminal capacitance	C_t	-	30	250	pF	-	$Ta=25^\circ C, V=0, f=1kHz$
Output	Operating supply voltage range	V_{CC}	15	-	30	v	-	$Ta=-10$ to $60^\circ C$
			15	-	24	v		
	O_1 Low level output voltage	V_{O1L}	-	0.2	0.4	v	1	$V_{CC1}=12V, V_{CC2}=-12V$ FS=OPEN $I_{O1}=0.1A, I_F=10mA, V_C=0V$
	O_2 High level output voltage	V_{O2H}	20	22	-	v	2	$V_{CC}=V_{O1}=24V, I_{O2}=-0.1A$ $I_F=10mA, FS=OPEN, V_C=0V$
	O_2 Low level output voltage	V_{O2L}	-	1.2	2.0	v	3	$V_{CC}=V_{O1}=24V, I_{O2}=0.1A$ $I_F=0mA, FS=OPEN, V_C=0V$
	O_1 Leak current	I_{O1L}	-	-	500	μA	4	$Ta=25^\circ C, V_{CC}=V_{O1}=35v$ $I_F=0mA, FS=OPEN, V_C=0V$
	High level supply current	I_{CCH}		10	17	mA	6	$Ta=25^\circ C, V_{CC}=V_{O1}=24V$ $I_F=10mA, FS=OPEN, V_C=0V$
			-		19	mA		$V_{CC}=V_{O1}=24V$ $I_F=10mA, FS=OPEN, V_C=0V$
Low level supply current	I_{CCL}		11	18	mA	6	$Ta=25^\circ C, V_{CC}=V_{O1}=24V$ $I_F=0mA, FS=OPEN, V_C=0V$	
				20	mA		$V_{CC}=V_{O1}=24V$ $I_F=0mA, FS=OPEN, V_C=0V$	

13/20

SHARP CORPORATION

MODEL No.
PC928PAGE
7

3.2 Electro-optical characteristics (1)

REFERENCE

(Unspecified : Ta=Topr)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Fig.	Conditions	
"L→H" threshold Input current *2	I_{FLH}	1.0	4.0	7.0	mA	5	Ta=25°C, Vcc=V _{O1} =24V FS=OPEN, Vc=0V	
		0.6	-	10			Vcc=V _{O1} =24V FS=OPEN, Vc=0V	
Isolation resistance	Riso	5×10 ¹⁰	10 ¹¹	.	Ω	-	Ta=25°C, DC=500V RH=40 to 60%	
Response time	"L→H" propagation time	t_{PLH}	-	1.0	2.0	μs	8	Ta=25°C
	"H→L" propagation time	t_{PHL}	-	1.0	2.0			Vcc=V _{O1} =24V, I _F =10mA
	Rise time	tr	-	0.2	0.5			R _G =47Ω, C _G =3000pF
	Fall time	tf	-	0.2	0.5			FS=OPEN, Vc=0V
Instantaneous common mode rejection voltage (High level output)	CM _H	-1500	-	.	v / μs	7	Ta=25°C I _F =10mA, Vcc=V _{O1} =24V ΔV _{OZH} =2.0V, FS=OPEN Vc=0V, V _{CM} =600V(peak)	
Instantaneous common mode rejection voltage (Low level output)	CM _L	1500	-	.	v / μs		Ta=25°C I _F =0mA, Vcc=V _{O1} =24V ΔV _{OZL} =2.0V, FS=OPEN Vc=0V, V _{CM} =600V(peak)	

- 1 It shall connect a by-pass capacitor of 0.01 μF or more between Vcc(Pin No. 13) and GND(Pin No. 10, 14) near the device, when it measures the transfer characteristics and the output side characteristics.

*2 I_{FLH} Is the value of forward current when output becomes from "L" to "H".

SHARP CORPORATION

MODEL No.

PC928

PAGE

8

3.2.2 Electro-optical characteristics(2)

REFERENCE

(Unspecified : Ta=Topr)

	Parameter	symbol	MIN.	TYP.	MAX.	unit	Conditions	Fig
Over current detection	Overcurrent detection voltage *4	V_{CTH}	$V_{CC}-6.1$	$V_{CC}-6$	$V_{CC}-5.5$	v	$T_a=25^{\circ}C$, $I_F=10mA$ $V_{CC}=V_{O1}=24V$ $R_G=47\Omega$ $C_G=3000pF$ $FS=OPEN$	
	Overcurrent detection voltage hysteresis width	V_{CHS}	1	2	3	v		
Protection output	O ₂ "H-L" propagation time at overcurrent protection	t_{PCOHL}	-	4	10	μs	$T_a=25^{\circ}C$ $V_{CC}=V_{O1}=24V$ $I_F=10mA$	
	O ₂ Fall time at overcurrent protection	t_{PCOF}	2	5		μs	$R_G=47\Omega$ $C_G=3000pF$	
	O ₂ output voltage at overcurrent protection	V_{OE}	1 -	-	2	v	$R_C=1k\Omega$ $C_p=1000pF$ $FS=OPEN$	
Error signal output	Low level error signal voltage	V_{FSL}		0.2	0.4	v	$T_a=25^{\circ}C$ $V_{CC}=V_{O1}=24V$ $I_F=10mA$ $I_{FS}=10mA$, $R_G=47\Omega$ $C_G=3000pF$ $C=OPEN$	
	High level error signal current	I_{FSH}			100	μA	$T_a=25^{\circ}C$ $V_{CC}=V_{O1}=24V$ $I_F=10mA$ $V_{FS}=24V$, $R_G=47\Omega$ $C_G=3000pF$ $V_C=0$	
	Error signal "H-L" propagation time	t_{PCFHL}		1	5	μs	$T_a=25^{\circ}C$ $V_{CC}=V_{O1}=24V$ $I_F=10mA$	
	Error signal output pulse width	Δt_{FS}	20	35		μs	$R_{FS}=1.8k\Omega$ $R_G=47\Omega$, $R_C=1k\Omega$ $C_G=3000pF$ $C_p=1000pF$	

- 3 It shall connect a by-pass capacitor of 0.01 μF or more between Vcc(Pin No.13) and GND(Pin No. 10, 14) near the device, when it measures the over current characteristics, protection output characteristics, and error signal output characteristics.

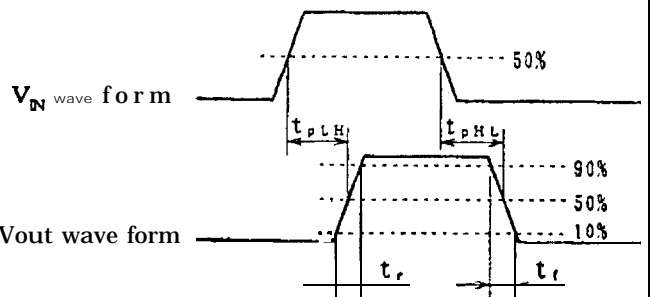
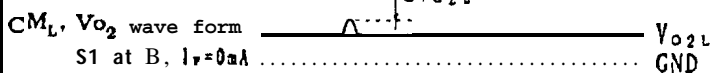
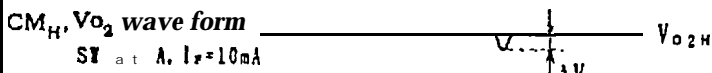
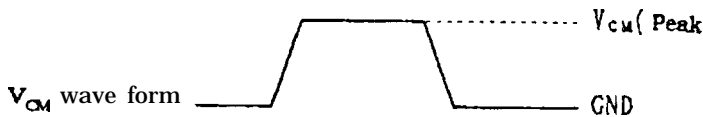
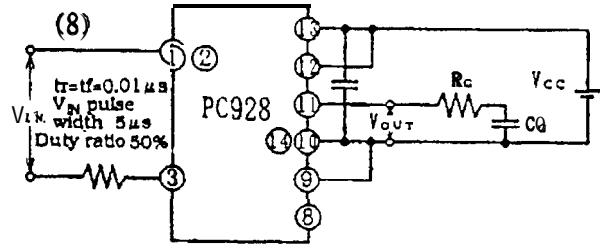
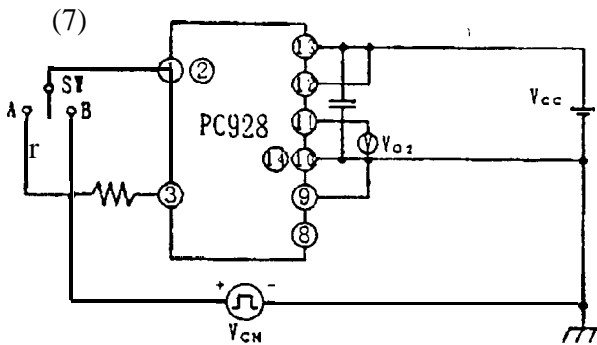
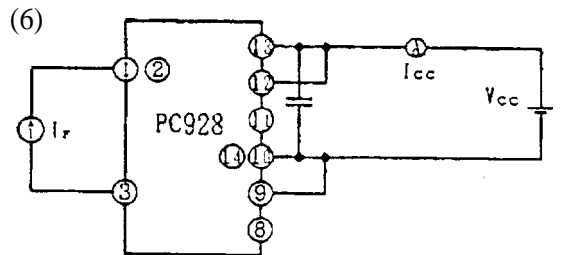
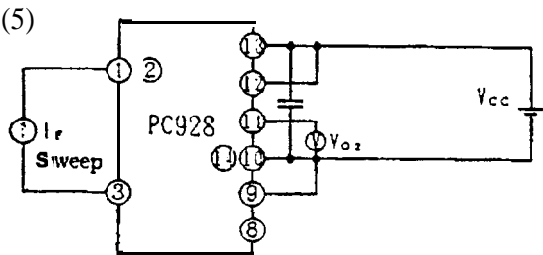
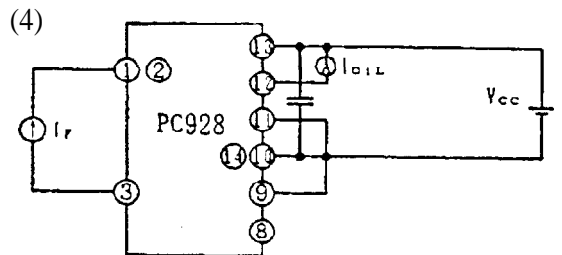
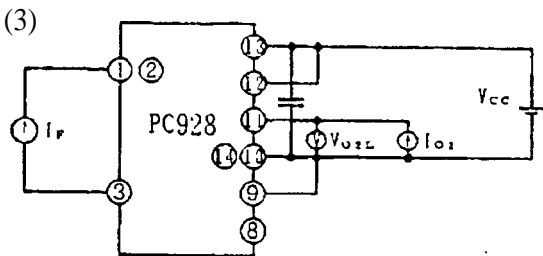
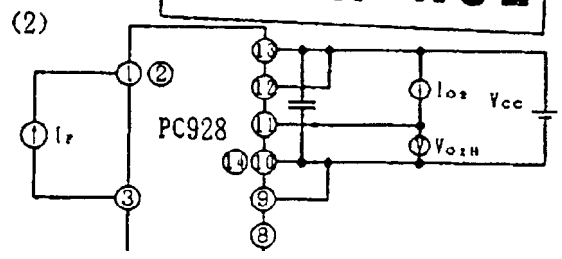
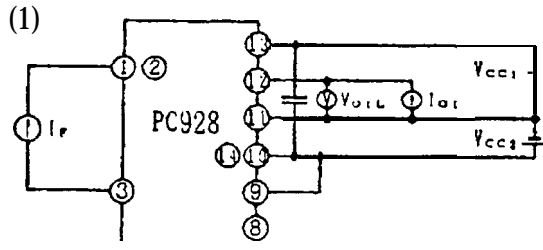
*4 V_{CTH} is the value of C(Pin No. 9) voltage when output becomes from "H" to "L".

15/20

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MODEL No. PC928	PAGE 9
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Test circuit (I)



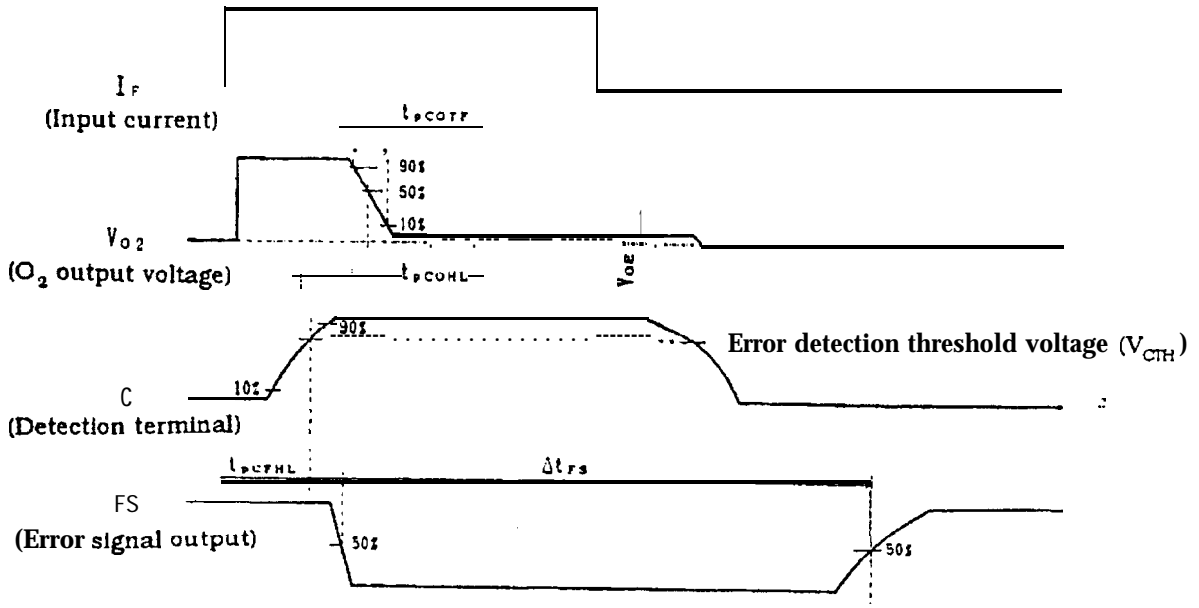
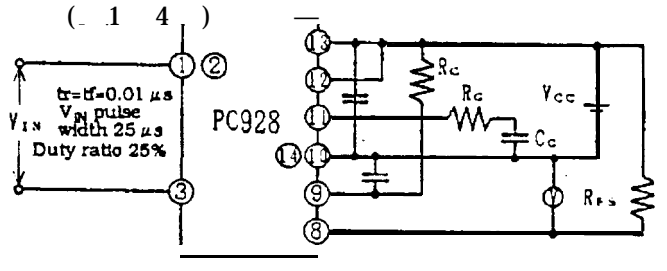
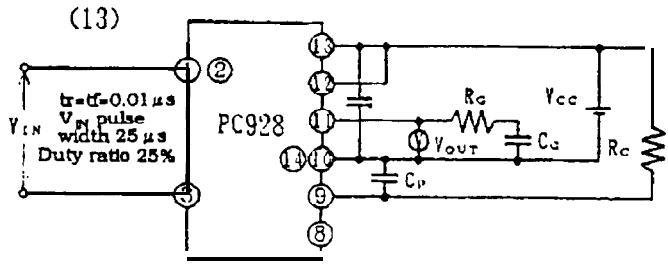
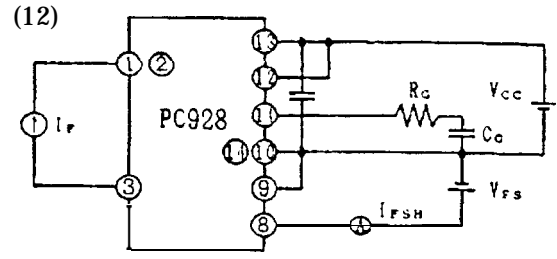
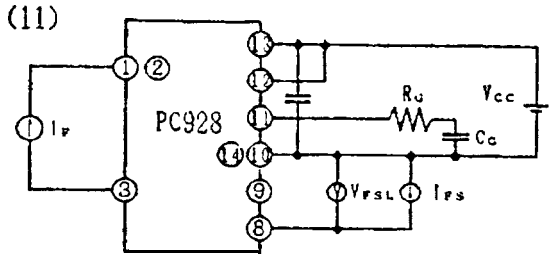
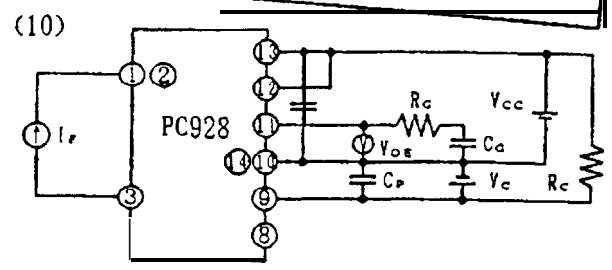
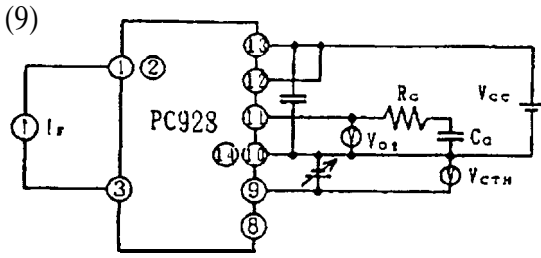
16/26

SHARP CORPORATION

MODEL NO. PC928	PAGE 10
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Test circuit(B)

REFERENCE



SHARP CORPORATION

MODEL No.

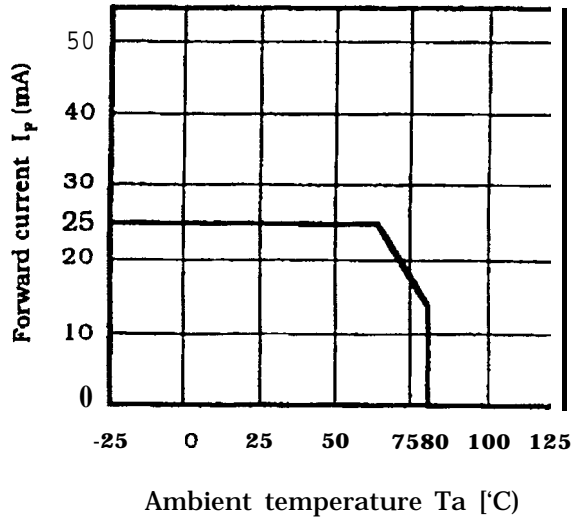
PC928

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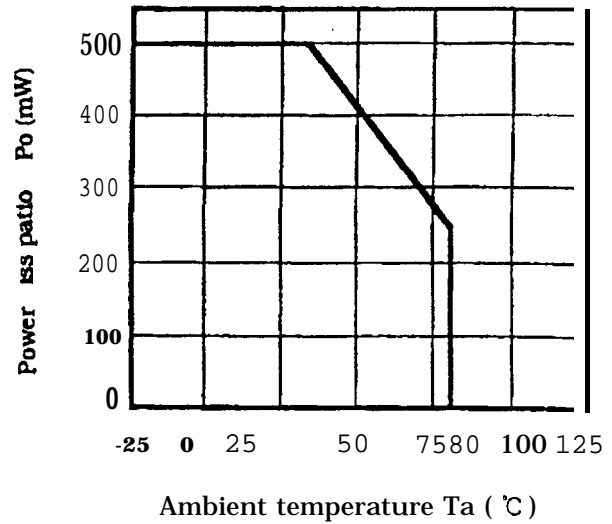
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17/
2.0**REFERENCE**

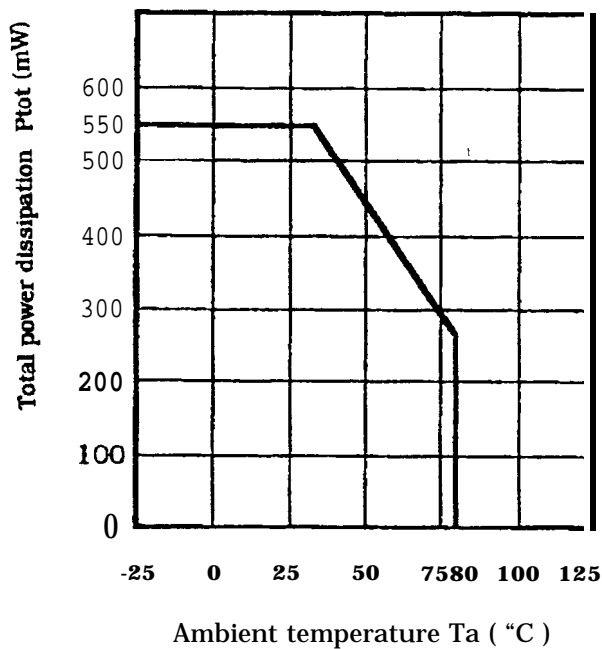
(Fig. 1) Forward current vs. ambient temperature



(Fig. 2) Output power dissipation vs. ambient temperature



(Fig. 3) Total power dissipation vs. ambient temperature



SHARP CORPORATION

MODEL No.

PC928

PAGE

12

4. Reliability

The reliability of products shall be satisfied with items listed below

REFERENCE

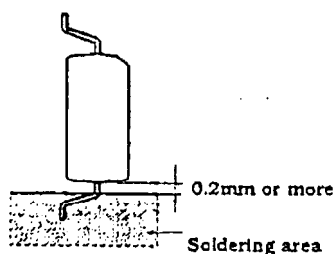
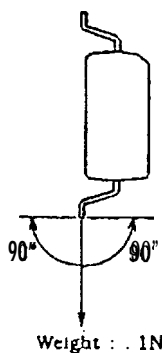
Confidence level: 90%
LTPD : 10°A/20%

Test Items	Test Conditions	Failure Judgement Criteria	Samples (n)
			Defective(C)
Solderability * 1	230°C, 5s	—	n=11, C=0
Soldering heat ● 2	260°C, 10 s	$V_F > U \times 1.2$	n=11, C=0
Terminal strength ● 3 (Bending)	Weight : 1 N 1 time/each terminal	$I_R > U \times 2$	n=11, C=0
Mechanical shock	15000 m/s ² , 0.5ms 3 times/ ±X, ±Y, ±Z direction	$V_{O1L} > U \times 1.2$ $I_{O2H} < L \times 0.8$	n=11, C=0
Variable frequency vibration	100 to 2000 to 100Hz/4min. 200m/s ² 4 ties/ X, Y, Z direction	$V_{O2L} > U \times 1.2$ $V_{O1L} > U \times 1.2$	n=11, C=0
Temperature cycling	1 cycle -55 °C to +125°C (30min.) (30*.) 20 cycle test	$I_{CCH} > U \times 1.2$ $I_{CCL} > U \times 1.2$	n=22, C=0
High temp. and high humidity storage	+60°C, 90%RH, 1000h	$I_{FLH} > U \times 1.3$	n=22, C=0
High temp. storage	+125°C, 1000h	U : Upper specification limit	n=22, C=0
Low temp. storage	-55°C, 1000h	L : Lower specification limit	n=22, C=0
Operation life	$I_F = 20mA$, $V_{CC} = 24V$ $T_a = 25°C$, 1000h		n=22, C=0

*1 Solder shall adhere at the area of 95% or more of immersed portion of lead and pin hole or other holes shall not be concentrated on one portion.

*2 The lead pin depth dipped into solder shall be away 0.2mm from the root of lead pins. (Refer to the below)

● 3 Terminal bending direction is shown below,



19/20

SHARP CORPORATION

MODEL No.
PC928PAGE
13

5. Incoming inspection

REFERENCE

5.1 Inspection Items

(1) Electrical characteristics

 $V_F, I_R, V_{O1L}, V_{O2H}, V_{O2L}, I_{O1L}, I_{CCH}, I_{CCL}, I_{FLH}, R_{iso}, V_{iso}$

(2) Appearance

5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on MIL-STD-105D is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	Inspection level	AQL (%)
Major defect	Electrical characteristics Unreadable marking	Normal inspection 11	0.1
Minor defect	Appearance defect except the above mentioned,	Normal inspection 11	0.4

20/
20

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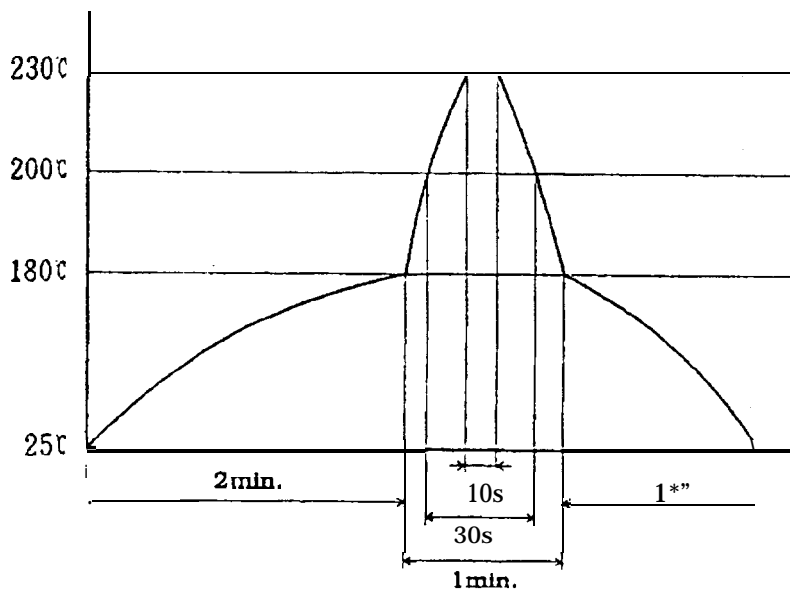
MODEL No. PC928	PAGE 14
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Precautions for Soldering Photocouplers

REFERENCE

1. If solder reflow :

It is recommended that **only one soldering be done** at the temperature and the **time within the temperature profile** as shown in the **figure**.



2. Other precautions

An infrared **lamp** used to heat up for soldering may cause a localized temperature rise in the resin, So keep the package temperature within that **specified in Item 1**, Also avoid **immersing** the resin part in the solder.

SHARP

Doc. No. : 5748

2/20

RELIABILITY TEST REPORT**Model No. : P C 9 2 8**

Please obey the instructions mentioned below for actual use of this device.
SHARP takes no responsibility for damage caused by improper use of the devices.

(1) This device is designed for general electronic equipment.

Main uses of this device are as follows;

[* Computer ● OA equipment .Telecommunication equipment (Terminal)
 .Measuring equipment .Tooling machine .AV equipment .Home appliance, etc.]

(2) please take **proper** steps in order to maintain reliability and safety, in **case** this device is used for the uses mentioned below which require high reliability.

[• Unit concerning control and safety of a vehicle (air plane, train, automobile etc.)
 .Traffic signal .Gas leak detection breaker .Fire box and burglar alarm box
 ● Other safety equipment, etc.]

(3) Please do not use for the uses **mentioned** below which **require** extremely high reliability.

[● Space equipment .Telecommunication equipment (Trunk)
 "Nuclear control equipment .Medical equipment etc.]

Contact a SHARP representative of sales office in advance when you intend to use SHARP devices for any applications other than those applications for general electronic equipment recommend by SHARP at(l).

Prepared by M. Sato
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Date : July 25, 1995 Dept. Q&RCC

Approved by Y. Uchida
Assistant Manager Y. Uchida

Date : July 26, '95 Dept. Q&RCC

Approved by Y. Kiyota
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Date : July 25, '95 Dept. Q&RCC

SHARP CORPORATION

Electronic Components Group

282-1, Hajikami, Shinjo-cho, Kitakatsuragi-gun

Nara 639-21 JAPAN

No: EPC-95740

3/20

RELIABILITY TEST REPORT

TYPE : PC 928

<RESULTS OF RELIABILITY TEST>

No.	Test Items	Test Conditions	Sample Size	Qty. of Failures
1	Solderability	230 ± 5°C, 5 ± 0.5s	11	0
2	Soldering Heat	260 ± 5°C, 10s	11	0
3	Terminal Strength (Bending)	Weight = 1N 0° → 90° → 0° 1cycles	11	0
4	Mechanical Shock	1500m/s ² , 0.5ms, ±X, Y, Z/3cycles	11	0
5	Vibration (Variable Frequency)	200m/s ² , 100 ~ 2000 ~ 100Hz/4min X, Y, Z/4cycles	11	0
6	Temperature Cycling	-55°C(30min)~125°C(30min) 20cycles	22	0
7	Thermal Shock	0°C ~ 100°C (5min)(5s)(5min) 20cycles	22 22	0 0
8	Moisture Resistance	-20°C ~ 70°C, 90%RH (2h) (1b) (2H) 40cycles	22	0
9	Humidity (Steady State)	Ta = 60°C, RH = 90%, t=1000h	22	0
10	High Temp. Storage	Ta = 125°C, t=1000h	22	0
11	Low Temp. Storage	Ta = -55°C, t=1000h	22	0
12	Operation Life	Ta = 25°C, IF = 20mA, VCC = 24V t=1000h	22	0

※ 1

※ 2

Acceptance limits of Parameters:

No.	Parameter	Acceptance limit
1	Forward voltage : V _F	U. S. L. × 1.2 ※ 3
2	Reverse current : I _R	U. S. L. × 2.0
3	Low level supply current : I _{CC L}	U. S. L. × 1.2
4	High level supply current : I _{CC H}	U. S. L. × 1.2
5	O ₁ low level output voltage : V _{O1 L}	U. S. L. × 1.2
6	O ₂ low level output voltage : V _{O2 L}	U. S. L. × 1.2
7	O ₂ High level output voltage: V _{O2 H}	L. S. L. × 0.8 ※ 4
8	O ₁ leak current : I _{OIL}	U. S. L. × 1.2
9	Threshold input current : I _{FLH}	U. S. L. × 1.3
10	O ₂ "H-L" propagation time : t _{PCOHL} at overcurrent protection	U. S. L. × 1.2
11	Overcurrent detection voltage : V _{CTH}	L. S. L. × 0.8 ~ U. S. L. × 1.2
12	Isolation voltage : V _{ISO}	5kVrms • AC 1 □ in .RH= 40 ~ 60% current limit ≤ 0.2mA

TE: ● XI The soldering area of terminal shall be covered greater than 95 percent.

※2 There shall be no evidence of breakage, loosening or relative motion between the terminal and package,

※3 The sign of U. S. L. represents Upper Specification limit,

※4 The sign of L. S. L. represents Lower Specification limit,

.Measuring condition of above parameters are based on this model's specification.

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4/20

